

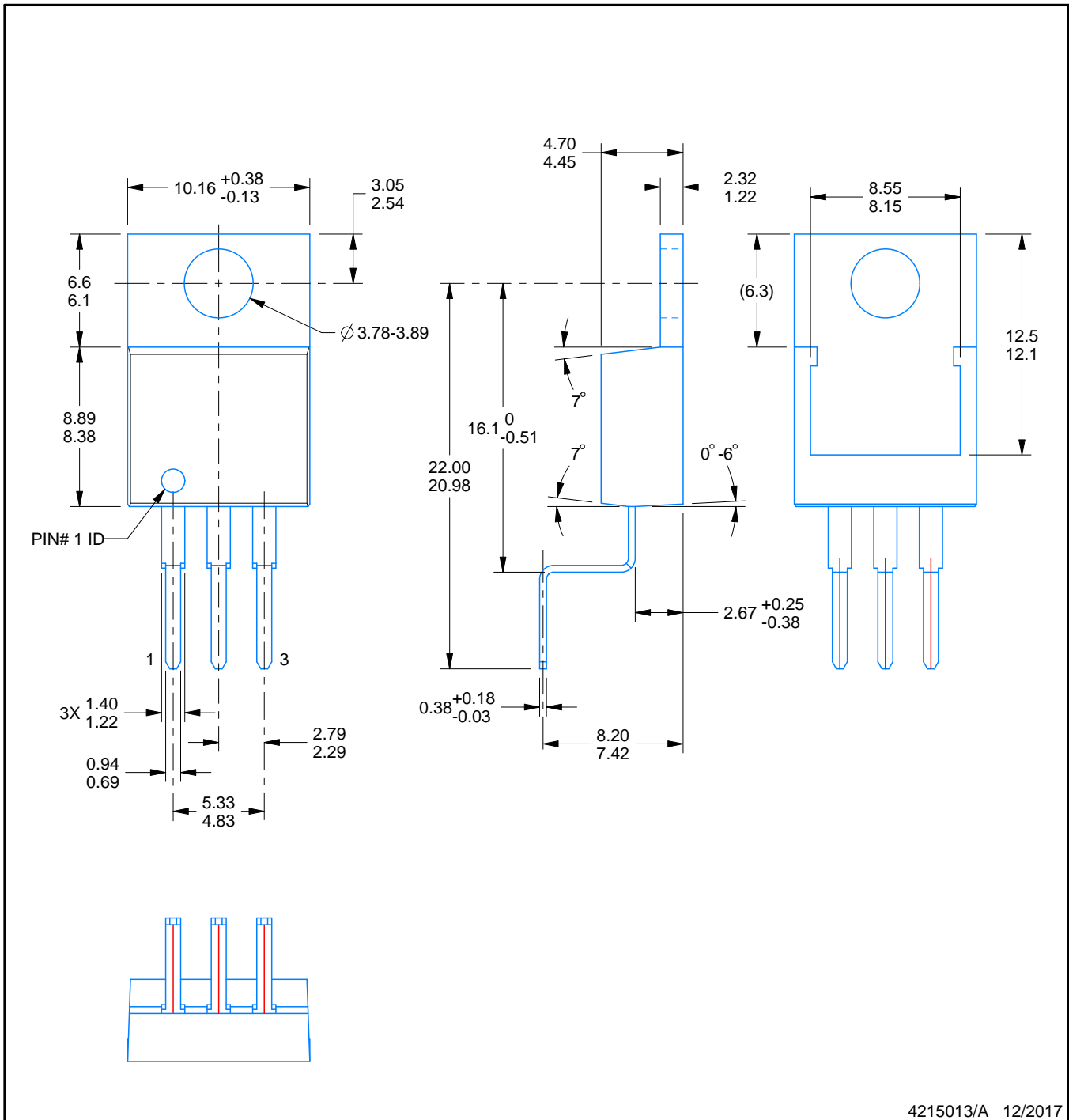


# NEB0003A

# PACKAGE OUTLINE

TO-220 - 19.65 mm max height

TRANSISTOR OUTLINE



4215013/A 12/2017

## NOTES:

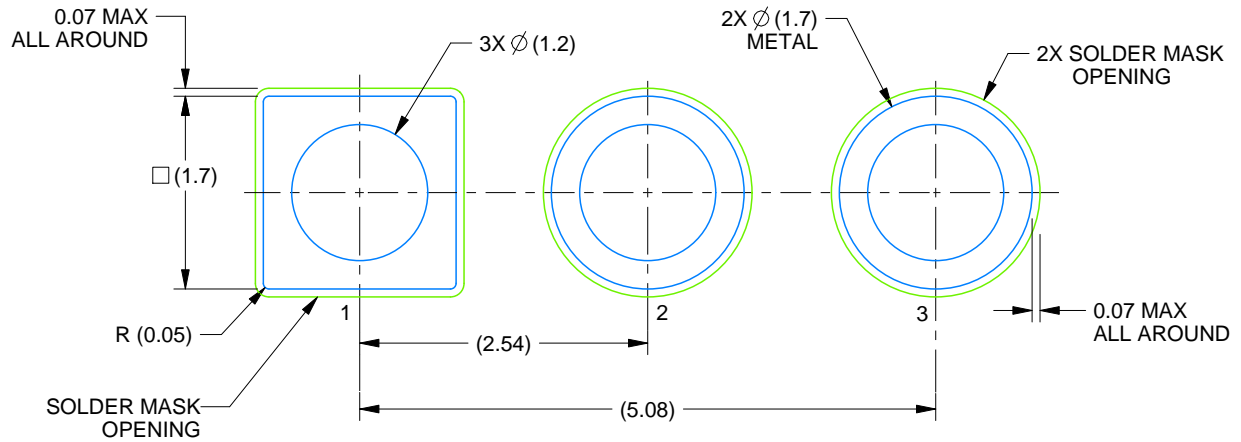
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-220.

# EXAMPLE BOARD LAYOUT

NEB0003A

TO-220 - 19.65 mm max height

TRANSISTOR OUTLINE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE:15X

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